



60V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| BV _{DSS} | R _{DS(ON)} Max | I _D Max T _C = +25°C |
|-------------------|-------------------------------|--|
| 60V | 18mΩ @ V _{GS} = 10V | 43A |
| | 20mΩ @ V _{GS} = 4.5V | 41A |

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Power Management Functions
- DC-DC Converters
- Industrial

Features

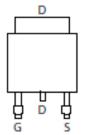
- Low On-Resistance
- Low Input Capacitance
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- · Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

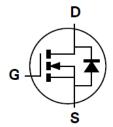
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Weight: 0.33 grams (Approximate)







Pin Out Top View



Equivalent Circuit

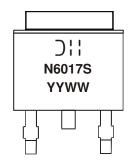
Ordering Information (Note 4)

| Part Number | Case | Packaging |
|---------------|--------------|-------------------|
| DMN6017SK3-13 | TO252 (DPAK) | 2,500/Tape & Reel |

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



Dili =Manufacturer's Marking
N6017S = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 17 = 2017)
WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | |
|--|----------------------------------|----------------|-----------|---|
| Drain-Source Voltage | V_{DSS} | 60 | V | |
| Gate-Source Voltage | V _{GSS} | ±20 | V | |
| 0 1 0 10 10 10 10 10 10 10 10 10 10 10 1 | $T_C = +25$ °C $T_C = +70$ °C | ID | 43 34 | А |
| Continuous Drain Current, V _{GS} = 10V (Note 5) | $T_A = +25$ °C $T_A = +70$ °C | I _D | 11 8.8 | Α |
| Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%) | I _{DM} | 70 | Α | |
| Maximum Continuous Body Diode Forward Current (Note 5) | I _S | 3.6 | Α | |
| Avalanche Current, L = 0.1mH | I _{AS} | 25 | Α | |
| Avalanche Energy, L = 0.1mH | E _{AS} | 32 | mJ | |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit | |
|--|----------------------------------|----------------|------|-------|
| Total Power Dissipation (Note 5) | $T_A = +25^{\circ}C$ | D | 3.3 | - w |
| Total Fower Dissipation (Note 5) | $T_{C} = +25^{\circ}C$ | P_{D} | 50 | |
| Thermal Resistance, Junction to Ambient (Note 5) | $R_{	heta JA}$ | 38 | °C/W | |
| Thermal Resistance, Junction to Case (Note 5) | | $R_{	heta JC}$ | 2.5 | 3G/VV |
| Operating and Storage Temperature Range | T _{J,} T _{STG} | -55 to +150 | °C | |

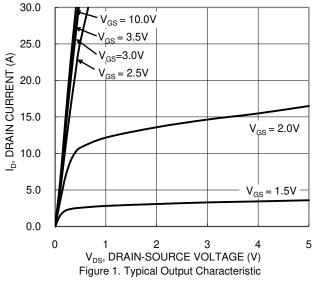
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

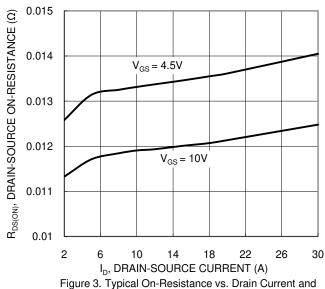
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|--|---------------------|--------|------|-------|-------|---|--|
| OFF CHARACTERISTICS (Note 6) | Syllibol | IVIIII | тур | IVIAX | Ullit | rest Condition | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 60 | _ | T _ | V | $V_{GS} = 0V$, $I_D = 250 \mu A$ | |
| Zero Gate Voltage Drain Current | IDSS | - | _ | 1 | μA | $V_{DS} = 48V, V_{GS} = 0V$ | |
| Gate-Source Leakage | | _ | _ | ±100 | nA | $V_{GS} = \pm 20V, V_{DS} = 0V$ | |
| Gate-Source Leakage $ I_{GSS} $ - $ \pm 100 $ nA $ V_{GS} = \pm 20V, V_{DS} = 0V$ ON CHARACTERISTICS (Note 6) | | | | | | VGS = ±20V, VDS = 0V | |
| Gate Threshold Voltage | V _{GS(TH)} | 1 | - | 3 | V | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$ | |
| 5 | | - | - | 18 | _ | V _{GS} = 10V, I _D = 6A | |
| Static Drain-Source On-Resistance | R _{DS(ON)} | - | - | 20 | mΩ | V _{GS} = 4.5V, I _D = 4A | |
| Diode Forward Voltage | V _{SD} | - | - | 1 | V | V _{GS} = 0V, I _S = 1A | |
| DYNAMIC CHARACTERISTICS (Note 7) | | | l . | | | , | |
| Input Capacitance | C _{iss} | - | 2711 | - | pF | | |
| Output Capacitance | Coss | - | 152 | - | pF | V _{DS} = 15V, V _{GS} = 0V, -f = 1MHz | |
| Reverse Transfer Capacitance | C _{rss} | - | 126 | - | pF | | |
| Gate Resistance | Rq | - | 1.4 | - | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ | |
| Total Gate Charge (V _{GS} = 4.5V) | Qg | - | 26 | - | nC | | |
| Total Gate Charge (V _{GS} = 10V) | Qq | - | 55 | - | nC | 10// 100// 100/ | |
| Gate-Source Charge | Q _{qs} | - | 6.2 | - | nC | $V_{DS} = 48V, I_{D} = 6A$ | |
| Gate-Drain Charge | Q _{qd} | - | 8.5 | - | nC | | |
| Turn-On Delay Time | t _{D(ON)} | - | 4.9 | - | ns | | |
| Turn-On Rise Time | t _R | - | 5.4 | - | ns | $\begin{aligned} V_{DD} &= 30 \text{V}, \ V_{GS} = 10 \text{V}, \\ R_g &= 3.3 \Omega, \ , \ I_D = 6 \text{A} \end{aligned}$ | |
| Turn-Off Delay Time | t _{D(OFF)} | - | 38.2 | - | ns | | |
| Turn-Off Fall Time | t _F | - | 11 | - | ns | | |
| Reverse Recovery Time | t _{RR} | - | 16.6 | - | ns | 1 00 4:/44 1000/ | |
| Reverse Recovery Charge | Q _{RR} | - | 10.3 | - | nC | $I_F = 6A$, di/dt = 100A/ μ s | |

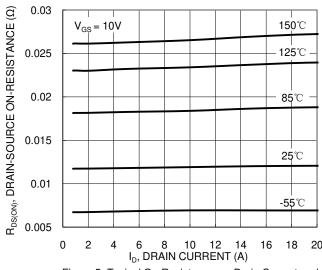
5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.



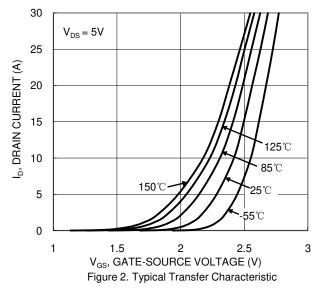


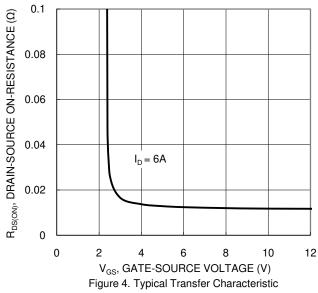




Gate Voltage

Figure 5. Typical On-Resistance vs. Drain Current and Temperature





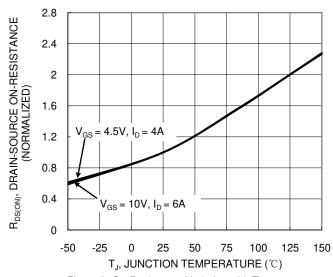


Figure 6. On-Resistance Variation with Temperature



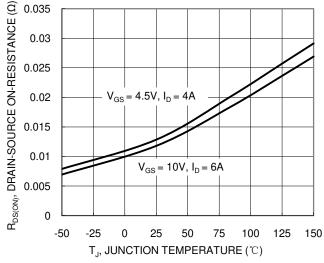


Figure 7. On-Resistance Variation with Temperature

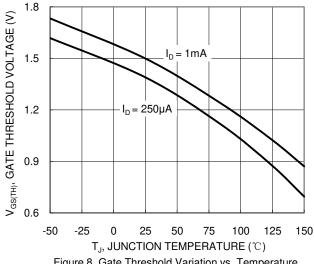
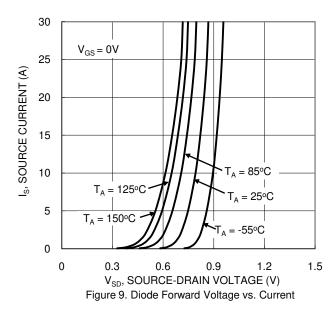


Figure 8. Gate Threshold Variation vs. Temperature



10000 f=1MHz C_T, JUNCTION CAPACITANCE (pF) $\mathsf{C}_{\mathsf{iss}}$ 1000 $\mathsf{C}_{\mathsf{oss}}$ 100 C_{rss} 10 0 15 20 25 35 40 V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 11. Typical Junction Capacitance

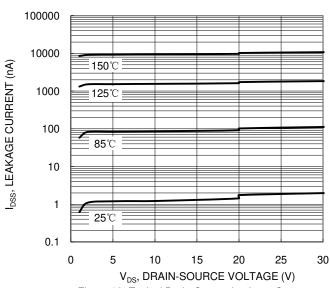
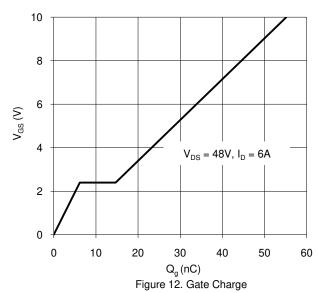
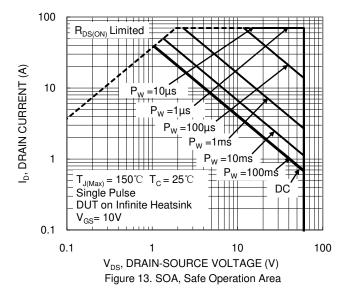


Figure 10. Typical Drain-Source Leakage Current vs. Voltage







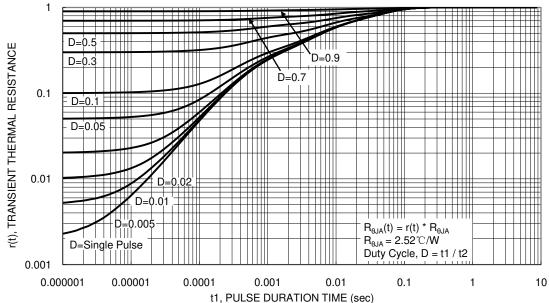
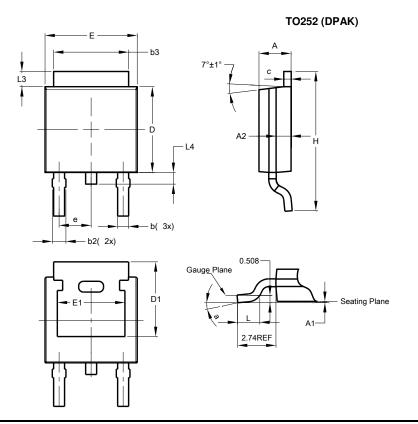


Figure 14. Transient Thermal Resistance



Package Outline Dimensions

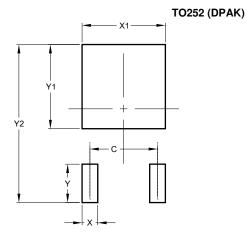
Please see http://www.diodes.com/package-outlines.html for the latest version.



| TO252 (DPAK) | | | | | |
|----------------------|------|-------|-------|--|--|
| Dim | Min | Max | Тур | | |
| Α | 2.19 | 2.39 | 2.29 | | |
| A1 | 0.00 | 0.13 | 0.08 | | |
| A2 | 0.97 | 1.17 | 1.07 | | |
| b | 0.64 | 0.88 | 0.783 | | |
| b2 | 0.76 | 1.14 | 0.95 | | |
| b3 | 5.21 | 5.46 | 5.33 | | |
| С | 0.45 | 0.58 | 0.531 | | |
| D | 6.00 | 6.20 | 6.10 | | |
| D1 | 5.21 | - | - | | |
| e | - | - | 2.286 | | |
| Е | 6.45 | 6.70 | 6.58 | | |
| E1 | 4.32 | - | - | | |
| Н | 9.40 | 10.41 | 9.91 | | |
| L | 1.40 | 1.78 | 1.59 | | |
| L3 | 0.88 | 1.27 | 1.08 | | |
| L4 | 0.64 | 1.02 | 0.83 | | |
| а | 0° | 10° | - | | |
| All Dimensions in mm | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



| Dimensions | Value (in mm) | | | |
|------------|---------------|--|--|--|
| С | 4.572 | | | |
| Х | 1.060 | | | |
| X1 | 5.632 | | | |
| Υ | 2.600 | | | |
| Y1 | 5.700 | | | |
| ٧o | 10.700 | | | |



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